

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S2	6	laser and scribe\$4 and wafer and saw\$3	JPO	OR	ON	2005/11/17 13:18
S3	36	laser and wafer and saw\$3	JPO	OR	ON	2005/11/17 13:18
S4	151	laser and scribe\$4 and wafer	JPO	OR	ON	2005/11/18 11:54
S5	1366	laser and (scribe\$4 cut\$4 etch\$4 ablate\$4 line street) and wafer	JPO	OR	ON	2005/11/18 11:54
S6	56	laser and (scribe\$4 cut\$4 etch\$4 ablate\$4 line street) and wafer and wafer	JPO	OR	ON	2005/11/18 12:00
S7	6	heinrich.xp. and (laser with (scribe\$4 cut\$4 etch\$4 ablate\$4 line street) with wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/18 12:05
S8	50	(laser with (scribe\$4 cut\$4 etch\$4 ablate\$4 line street) with wafer) and (laser with (plural\$4 multiple\$4 repeat\$4 adjacent) near (line street scribe track))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/18 12:25